

## YES-G500 Plasma Cleaning System

For Wire Bond Surface Preparation and Gentle Cleaning Applications

## **Specifications**

Hardware	
Clean Room Compatibility	Class 10
Operation Temperature	145 °C maximum
N <sub>2</sub> Flow Rate	1.0 SCFM
Process Gas Flow Rate	0.6 x 10 <sup>-3</sup> SCFM @ 150 Mtorr, 12 CFM PUMP
	1.2 x 10 <sup>-3</sup> SCFM @ 150 Mtorr, 19 CFM PUMP
Interior Chamber Dimensions	45.72 cm (W) x 45.72 cm (D) x 20.955 cm (H)
	(18" x 18" x 8.25")
Chamber Process Area	700 in <sup>2</sup> maximum (mode dependent) or 233 in <sup>2</sup> per shelf
Overall System Dimensions	59.69 cm (W) x 71.2 cm (D) x 103.81 cm (H)
	(23.5" x 28.03" x 40.87")
	light tower adds 27 cm to height (10.62")
Chamber Material	6061-T6 aluminum
Process Gas Inputs	3 standard, 4 <sup>th</sup> optional
Mass Flow Controllers	Optional, up to 3 for gas mixing
SEMI <sup>TM</sup> Compliance	S2 compliance
Software	
Number of Recipes	12 with load/save/loop/link capability
Range of Exposure Time	0-1200 seconds (20 minutes)
Resolution of Timer Setting	1 second
Performance	
RF Plasma Power	100-500 watts
RF Leakage Magnetic	$0.5 \text{ m from front}$ ; $0.84 \text{ mA/m}$ , $7.06 \times 10^{-7} \text{ A}^2/\text{m}^2$
	0.5 m from rear; 0.35 mA/m, 1.23 x $10^{-7}$ A <sup>2</sup> /m <sup>2</sup>
RF Leakage Electrical	$0.5 \text{ m from front}$ ; $2.89 \text{ V/m}$ , $8.35 \text{ V}^2/\text{m}^2$
	$0.5 \text{ m from rear}$ ; $0.24 \text{ V/m}$ , $0.06 \text{ V}^2/\text{m}^2$
Nitrogen Consumption	0 SCF idle, 6.8 SCF peak, 1.7 SCF average
Power Consumption with Pump	375W idle, 1000W peak, 640W average
Reactant Gas Consumption	0 SCF idle, 20-50 SCCM
Heat Emission	920 watts average
Additional	
Power Requirements	208-230V, 20 amps, 50/60 Hz, 1 phase
System Weight	147 kg (325 lbs)



## **Contact Us**

When you're ready to run process tests, a demonstration can be arranged using your chemicals and samples. Call +1 925-373-8353 (worldwide), 1-888-YES-3637 (US toll free), or visit us online at <a href="https://www.yieldengineering.com">www.yieldengineering.com</a>.

©2012 Yield Engineering Systems. Yield Engineering Systems and the Yield Engineering Systems logo are trademarks of Yield Engineering Systems, Inc. All other brands, product names and logos are trademarks or service marks of their respective owners. All specifications subject to change without notice. Individual process results may vary.